ABSTRACT

A manufacturing method of a semiconductor element substrate includes: a step of forming a first photoresist pattern on a first surface of a metallic plate, to form a semiconductor element mounting part, a semiconductor element electrode connection terminal, a wiring, an outer frame part, and a slit; a step of forming a second photoresist pattern on the second surface of the metallic plate to form an external connection terminal, the outer frame, and the slit; a step of forming the slit by half etching to connect the metallic chip with a four corners of the outer frame part, the metallic chip being a part of the metallic plate; a step of forming a plurality of concaved parts on the second surface of the metallic plate; a step of forming a resin layer by injecting a resin to the plurality of concaved parts so that the resin does not enter the slit and hardening the resin; and a step of etching the first surface of the metallic plate and forming the semiconductor element electrode connection terminal and the outer frame, both being electrically connected to the semiconductor element mounting part and the external connection terminal.

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